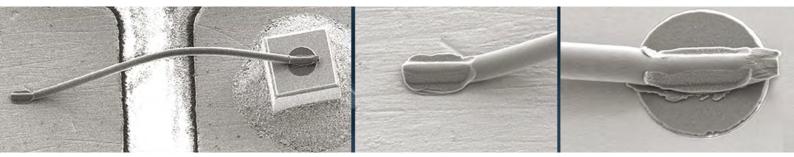


VERSATILITY ACROSS ALL PACKAGING APPLICATIONS
STRONGER HEEL
HIGHER BOND PULL STRENGTH





VERSATILITY IN DESIGN AND PERFORMANCE

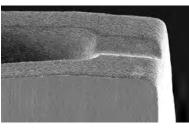


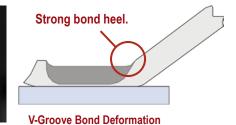
Photos courtesy of ASM (Bonder Model: Cheetah II)

The adaptation of V-groove wedge design popularly used for heavy Aluminum wire application is now available for small Aluminum wire wedge tool design (1.0 mil - 2.0 mil) optimized by SPT to improve bondability and product reliability to the next level.

Benefits of V-Groove design features:

- Enhances wire coupling for efficient ultrasonic energy transfer providing consistent bond quality.
- Stronger heel for higher bond pull strength readings.
- Ensures wire is centered underneath the wedge foot for consistent bond placement.
- More tool contact compared with conventional flat or concave foot design.





STANDARD DIMENSIONS	

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Part Number	Wire Diameter (WD)	Bond Flat (BF)
	mils [µm]	inch [mm]
AV-1815-L-VGM 2015665	1.00 [25]	.0015 [0.038]
AV-1820-L-VGM 2015668	1.00 [25]	.0020 [0.051]
AV-1825-L-VGM 2015670	1.00 [25]	.0025 [0.064]
AV-2015-L-VGM 2015672	1.25 [32]	.0015 [0.038]
AV-2020-L-VGM 2015673	1.25 [32]	.0020 [0.051]
AV-2025-L-VGM 140-10553	1.25 [32]	.0025 [0.064]

